

HiTemp ET Series Thermoelectric Cooler

Note: This product is not recommended for new designs.

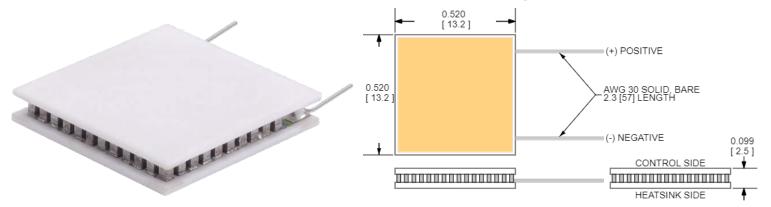
This product series has been replaced with the HiTemp ETX Series. Currently there is no standard HiTemp ETX Series replacement for this part. Contact Sales for available options.

Features

- High-temperature operation
- Reliable solid-state
- No sound or vibrationEnvironmentally-friendly
- RoHS-compliant

Applications

- Peltier Cooling for Refrigerated Centrifuges
- Peltier Cooling for Machine Vision
- Thermoelectric Cooling for CMOS Sensors
- Cooling Solutions for Autonomous SystemsPeltier Cooling for Digital
- Light Processors

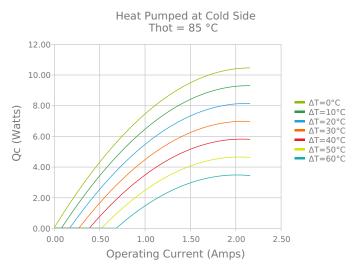


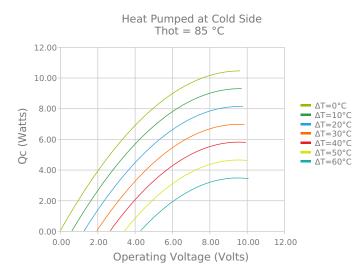
CERAMIC MATERIAL: Al₂O₂ SOLDER CONSTRUCTION: 232°C, SbSn

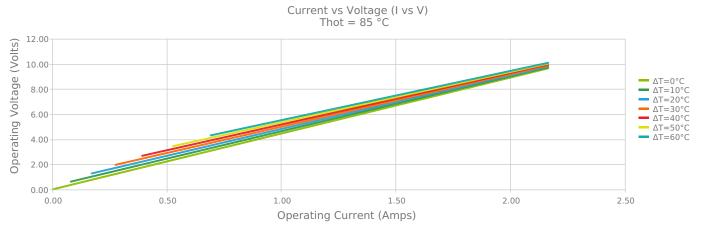
INCHES [MM]

ELECTRICAL AND THERMAL PERFORMANCE

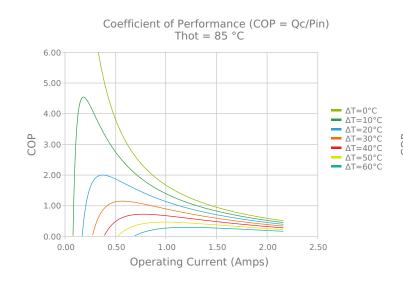
For maximum performance, be sure to orient the CONTROL side of the TEC against the application to be managed and the HEATSINK side against the heat sink or other heat rejection method. The CONTROL side is always opposite the side with lead attachments. Lead attachment is a passive heat loss and less impactful if located on the side that attaches to the heat exchanger.

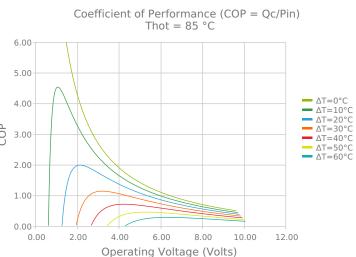


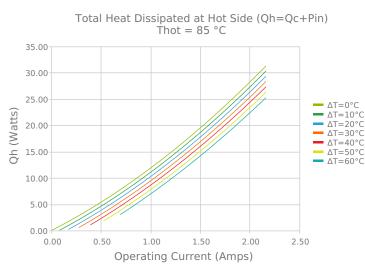


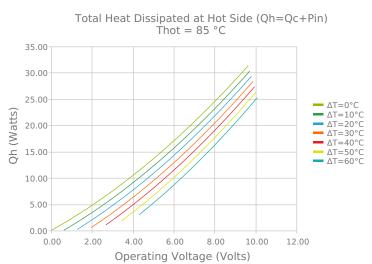


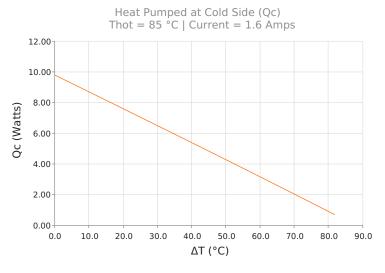


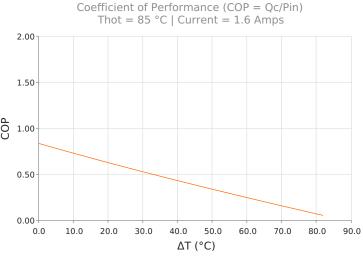














SPECIFICATIONS*

Hot Side Temperature

 $Qcmax (\Delta T = 0)$

 $\Delta T max (Qc = 0)$

Imax (I @ ATmax)

Vmax (V @ Δ Tmax)

Module Resistance

Max Operating Temperature

Weight

50.0 °C	85.0 °C	110.0 °C
9.5 Watts	10.4 Watts	10.9 Watts
77.9°C	89.3°C	96.2°C
2.0 Amps	1.9 Amps	1.9 Amps
8.2 Volts	9.4 Volts	10.2 Volts
3.83 Ohms	4.45 Ohms	4.87 Ohms
150 °C		
2.0 gram(s)		

FINISHING OPTIONS

Suffix	Thickness	Flatness / Parallelism	Hot Face	Cold Face	Lead Length
GG	2.515 ±0.127 mm 0.099 ± 0.0050 in	N/A / N/A	Au Plated	Au Plated	50.8 mm 2.00 in

SEALING OPTIONS

Suffix	Sealant	Color	Temp Range	Description
	None			No sealing specified

NOTES

- 1. Max operating temperature: 150°C
- 2. Do not exceed Imax or Vmax when operating module
- 3. Reference assembly guidelines for recommended installation

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^{*} Specifications reflect thermoelectric coefficients updated March 2020